

DIE BONDER

# T-3000-FC3

The **T-3000-FC3** series is Tresky's most flexible die bonding platform. The systems can run all basic functions as well as the industries most advanced applications by adding a wide range of available options. As with all of Tresky's products, the FC3 incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height. Together with superior ergonomics the FC3 platform is the industry's most sophisticated system in its class.

True Vertical Technology™

Ultra precise bond-height control

Multi functional software

Up to 500N Bond-Force

MICRO ASSEMBLY

T-3000-FC3



# TRESKY

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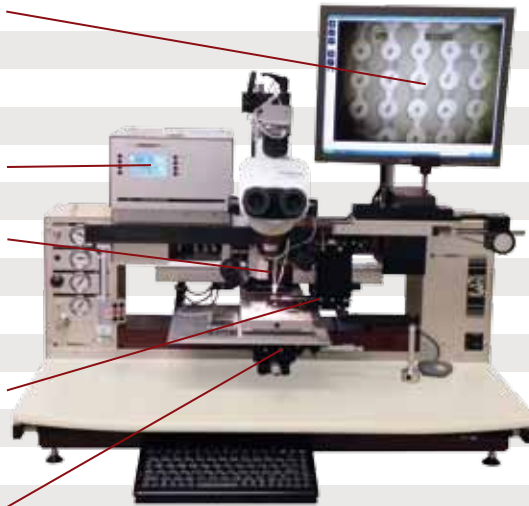
Advanced multi functional die bonder with superior ergonomic design and programmable, high accuracy Z-Drive and bond-force control.

### APPLICATIONS:

Die Attach, Flip-Chip, Thermocompression, 3D Packaging, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermo-sonic, RFID, Sensor Assembly, Adhesive Bonding, Eutectic Bonding (AuAu, .....), .....

### FEATURES AND OPTIONS:

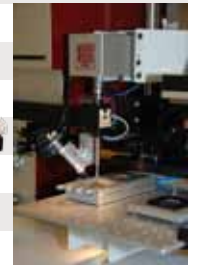
- Interface for temperature profile and video imaging
  - > HD Image of Beam Splitter Optics
  - > Process Inspection Camera
- Programmable Z-Drive with Bond-Force Control
- TRUE VERTICAL TECHNOLOGY™ Z-movement 95mm with 360° tool rotation; Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre-Form Spindle, ...
- Flip-Chip09mpa Beam Splitter with multi point alignment
  - > 1µm placement accuracy
- XY placement stage with micrometer screws supporting:  
Waffle- / Gel- Pack -, Substrate Holder, various Heating Plates



Low Bond Force



High Bond Force



### TECHNICAL DATA:

XY- Movement (placement stage):	220mm x 220mm (manual)
Z- Movement:	95mm (automatic)
Spindle Rotation:	360°
Bond Force (standard range):	20g - 400g; Optional up to 50Kg
Bond Force (repeatability):	±1g
Z-Measurement resolution:	±0.001mm
Max. PC Board-/ Substrate Size:	400mm x 280mm
Placement accuracy:	10µm; 1µm with high accuracy beam splitter (Flip-Chip09mpa)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	900mm x 800mm x 700mm
Weight:	85kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

### REPRESENTED BY:

#### HEADQUARTERS

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